

ABSTRACT

Provided are an electronic device sealing resin sheet that is capable of forming a mark excellent in visibility by laser marking, and a method for manufacturing an electronic device package. The electronic device sealing resin sheet according to the present invention is an electronic device sealing resin sheet including a first resin layer and a second resin layer. In this sheet, between a marked region obtained after laser marking is applied to the first resin layer and a region other than the marked region, a contrast of 20% or more is shown.